POLISHING COMPOSITION AND POLISHING METHOD

ABSTRACT

A polishing composition contains silica abrasive grains having an average particle size of 20 to 100 nm, an alkali selected from the group consisting of ammonia, ammonium salts, alkali metal salts, and alkali metal hydroxides, and a silicone oil having an HLB value greater than or equal to 8. The polishing composition is suitable for use in an application for polishing an object to be polished.